



Final Product Change Notification

201807015F01

Issue Date: 15-Aug-2018

Effective Date: 12-Nov-2018

Dear *Tracy Hoglin*,

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

ESOIC and HTSOIC Die Attach Epoxy Migration to Alpha Metal 800HT5

Description of Change

NXP Semiconductors announces the qualification of new die attach epoxy Alpha Metal 800HT5 for the ESOIC and HTSOIC products associated with this notification. Product will migrate from the current Namics J154-5 die attach epoxy to the new Alpha Metal 800HT5. The change is only applicable to the power die conductive epoxy, while the control die non-conductive epoxy remains unchanged.

The new Alpha Metal 800HT5 die attach epoxy offers a more robust manufacturing solution with reduced epoxy bleeding / reduced opportunity for cross-contamination of dissimilar conductive and non-conductive epoxy materials. Alpha Metal 800HT5 die attach epoxy has been qualified according to automotive requirements.

Please see attached qualification strategy and results for details.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-07 and SEM-PA-16.

Reason for Change

Alpha Metal 800HT5 provides improved conductive die attach epoxy manufacturing solution with enhanced quality for ESOIC and HTSOIC packages.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available from 13-Nov-2018

Production

Planned first shipment 01-Jan-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 14-Sep-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Antoine Storez

Position Quality Engineer

e-mail address antoine.storez@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[NXP](#) | [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.

Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
MC34932EK	935315126574	MC34932EK	DUAL 5A THROTTLE CONTROL	SOT1747-4	HSOP54	RFS	BL Advanced Automotive Analog
MC08XS6421BEK	934070614574	MC08XS6421BEK	Quad High Side Switch	SOT1746-2	HSOP32	RFS	BL Power MOS FSL
MC33931EK	935312312574	MC33931EK	5A H-BRIDGE	SOT1746-1	HSOP32	RFS	BL Advanced Automotive Analog
MC34931SEK	935318327574	MC34931SEK	5A H-BRIDGE	SOT1746-1	HSOP32	RFS	BL Advanced Automotive Analog
MC33932EK	935314523574	MC33932EK	DUAL 5A THROTTLE CONTROL	SOT1747-4	HSOP54	RFS	BL Advanced Automotive Analog
MC34931EK	935311557574	MC34931EK	5A H-BRIDGE	SOT1746-1	HSOP32	RFS	BL Advanced Automotive Analog
MC33931EKR2	935312312518	MC33931EKR2	5A H-BRIDGE	SOT1746-1	HSOP32	RFS	BL Advanced Automotive Analog
MC34932SEK	935311993574	MC34932SEK	5A H-BRIDGE	SOT1747-4	HSOP54	RFS	BL Advanced Automotive Analog
MC33HB2001EK	935318112574	MC33HB2001EK	H-Bridge DC Motor Dr	SOT1746-1	HSOP32	RFS	BL Advanced Automotive Analog